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Apparatus for the automatic production of a series arrangement of wafer-like electronic parts
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#Abstract:
Apparatus for the automatic production of a series arrangement containing electronic parts, by means of a receiving body provided with receiving orifices, in which electronic parts designed without junction wires are accommodated. In the apparatus working automatically, a band-shaped receiving body is moved intermittently in the longitudinal direction and wafer-like electronic parts are supplied successively by a feed device, specifically into each receiving orifice of the receiving body in the direction of transport. The receiving orifice is closed by a band-shaped covering strip when the part is fed in. The covering strip is applied to the receiving body by an applicator device, whereupon the series arrangement containing the electronic parts is wound onto a drum in a winding device.